



APPENDIX D

**(VERSION OF CLAIMS AS AMENDED HEREIN
WITH MARKINGS TO SHOW CHANGES MADE)**

(Serial No. 09/942,245)

VERSION OF CLAIMS WITH MARKINGS TO SHOW CHANGES MADE

10. (Amended) A semiconductor assembly comprising:
- a semiconductor device having an active surface;
 - a substrate having an upper surface;
 - a wetting agent located on a portion of one of said active surface of said semiconductor
 - [die]device and said upper surface of said substrate; and
 - an underfill material located between said substrate and said semiconductor device.